

## AMENDMENTS TO THE CLAIMS

Claims 1-20 (cancelled)

Claim 21 (original): An integrated structure including a semiconductor device and connector structures for connecting the semiconductor device to a motherboard, the integrated structure comprising:

- a first layer having a first set of conductors disposed therein, the first layer having an upper surface and a lower surface, the first set of conductors connecting to bonding pads disposed on the lower surface, the bonding pads being spaced with respect to each other with a first spacing distance in accordance with a required spacing of connections to the motherboard;

- the semiconductor device;

- a second layer disposed on the semiconductor device and in contact therewith, the second layer having a second set of conductors disposed therein connecting to the semiconductor device, the second layer facing the first layer;

- a plurality of connectors connecting the first set of conductors to the second set of conductors, said connectors being one of (1) a set of stud/via connectors and (2) a set of C4 connectors, said connectors being spaced with respect to each other with a second spacing distance less than the first spacing distance;

- a support structure attached to the upper surface of the first layer and surrounding the semiconductor device, a gap between said support structure and the semiconductor device being filled with a fill material; and

- connector structures connected to the bonding pads.

Claim 22 (original): An integrated structure according to claim 21, wherein the connector structures form one of a pin grid array (PGA), a ball grid array (BGA), a C4 array and a land grid array (LGA).

Claim 23 (original): An integrated structure according to claim 21, wherein the motherboard is characterized by a thermal coefficient of expansion (TCE), and the support structure is provided with a TCE approximately that of the motherboard.

Claim 24 (original): An integrated structure according to claim 21, wherein the support structure has an area corresponding to an area occupied by the bonding pads.

Claim 25 (original): An integrated structure according to claim 21, wherein said plurality of connectors are a set of C4 connectors, and the fill material fills a gap between the semiconductor device and the first layer surrounding said C4 connectors.

Claim 26 (original): An integrated structure according to claim 21, wherein said plurality of connectors are a set of stud/via connectors, and said integrated structure further comprises a third layer interposed between the first layer and the second layer and having vias formed therein.